











**TDC7200** 

ZHCSDF0C -FEBRUARY 2015-REVISED AUGUST 2015

# TDC7200 适用于激光雷达飞行时间、磁致伸缩和流量计应用的时间数字转 换器

## 特性

- 分辨率: 55ps
- 标准偏差: 35ps
- 测量范围:
  - 模式 1: 12ns 至 500ns
  - 模式 2: 250ns 至 8ms
- 低功耗: 0.5µA (2SPS)
- 最多支持 5 个 STOP 信号
- 自主多周期平均模式, 可实现低功耗
- 电源电压: 2V 至 3.6V
- 工作温度范围: -40°C 至 85°C
- 用于配置和寄存器访问的 SPI 主器件接口

#### 2 应用

- 流量计: 水表、燃气表和热量计
- 磁致伸缩位置/液位感测
- 无人机(激光雷达和声纳)的飞行时间、计量设备 和投影仪
- 热量分配表

#### 3 说明

TDC7200 是一款时间 - 数字转换器 (TDC),适用于水 表、燃气表和热量计等超声波感测装置。 与 TDC1000 (超声波模拟前端)配套使用时,TDC7200可与 MSP430、电源、无线器件以及相关源代码一起构成一 套完整的德州仪器 (TI) 超声波感测解决方案。

时间数字转换器 (TDC) 可执行秒表功能,测量 START 脉冲与多达 5 个 STOP 脉冲之间的时间间隔(渡越时 间,即 TOF)。 这一功能使得用户能够灵活选择回声 性能最佳的 STOP 脉冲。

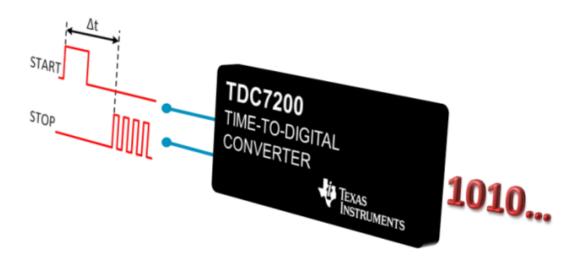
该器件内置自校准时基, 可对时间和温度偏差进行补 偿。 这一自校准功能使得时间数字转换器能够获得皮 秒级精度。 因此, TDC7200 非常适用于注重高精度零 流量和低流量测量的流量计应用。

TDC7200 置于自主多周期平均模式下时,可降低系统 功耗,非常适合电池供电式流量计。 在此模式下,主 器件会进入休眠模式以实现节能,并会在测量序列完成 后由 TDC 中断唤醒。

## 器件信息<sup>(1)</sup>

部件号	封装	封装尺寸 (标称值)
TDC7200	TSSOP (14)	5.00mm x 4.40mm

(1) 要了解所有可用封装,请见数据表末尾的可订购产品附录。





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# 4 修订历史记录

Changes from Revision B (June 2015) to Revision C	Page
• 已将数据表标题由 TDC7200 适用于水和燃气流量感测、磁致伸缩位置感测以及激光雷达计量应用的时间 - 数字转器 器更改为 TDC7200 适用于激光雷达飞行时间、磁致伸缩和流量计应用的时间 - 数字转换器	
Changes from Revision A (March 2015) to Revision B	Page
<ul> <li>已将数据表标题由 TDC7200 适用于水、燃气、热量计量应用的时间-数字转换器更改为 TDC7200 适用于水和燃气流量感测、磁致伸缩位置感测和激光雷达计量应用的时间-数字转换器</li> <li>已更改应用列表,新增了"磁致伸缩位置感测"和"激光雷达计量"</li> </ul>	1
Changes from Original (February 2015) to Revision A	Page
己更改 "单页产品预览"至"完整数据表"      Changed ESD Ratings table	

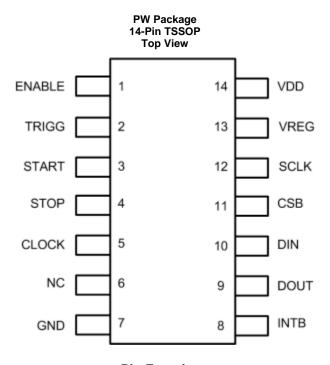


# 5 Companion Device

PART NO.	TITLE
TDC1000	Ultrasonic Sensing Analog Front End for Level, Concentration, Flow and Proximity Sensing



# 6 Pin Configuration and Functions



#### **Pin Functions**

Р	PIN	1/0	DECORPTION	
NAME	NO.	I/O	DESCRIPTION	
ENABLE	1	Input	Enable signal to TDC	
TRIGG	2	Output	gger output signal	
START	3	Input	START signal to TDC	
STOP	4	Input	STOP signal to TDC	
CLOCK	5	Input	Clock Input to TDC	
N.C.	6	_	Not Connected	
GND	7	Ground	ound	
INTB	8	Output	Interrupt to MCU, active low (open drain)	
DOUT	9	Output	SPI Data Output	
DIN	10	Input	SPI Data Input	
CSB	11	Input	SPI Chip Select, active low	
SCLK	12	Input	SPI clock	
VREG	13	Output	LDO Output terminal for external decoupling cap	
VDD	14	Power	Supply input	



## 7 Specifications

## 7.1 Absolute Maximum Ratings

 $T_A = 25$ °C , VDD = 3.3V, GND = 0V (unless otherwise noted). (1)(2)(3)

		MIN	MAX	UNIT
		IVIIIN	WAX	UNII
$V_{DD}$	Supply voltage	-0.3	3.9	V
$V_{I}$	Terminal input voltage	-0.3	V <sub>DD</sub> +0.3	V
$V_{DIFF\_IN}$	Voltage differential  between any two input terminals		3.9	V
$V_{IN\_GND\_V}$	Voltage differential  between any input terminal and GND or VDD		3.9	V
DD				
I <sub>I</sub>	Input current at any pin	<del>-</del> 5	5	mA
T <sub>A</sub>	Ambient temperature	-40	125	°C
T <sub>stg</sub>	Storage temperature	-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## 7.2 ESD Ratings

			VALUE	UNIT
		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±1000	
V <sub>(ESD)</sub>	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±250	V

<sup>(1)</sup> JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

## 7.3 Recommended Operating Conditions

 $T_A = 25$ °C , VDD = 3.3V, GND = 0V (unless otherwise noted).

		MIN	NOM	MAX	UNIT
$V_{DD}$	Supply voltage	2		3.6	V
$V_{I}$	Terminal voltage	0		VDD	V
$V_{IH}$	Voltage input high	0.7 × VDD		3.6	V
$V_{IL}$	Voltage input low	0		0.3 × VDD	V
F <sub>CALIB_CLK</sub>	Frequency (Reference/Calibration Clock)	1 (1)	8	16	MHz
DUTY <sub>CLOCK</sub>	Input clock duty cycle		50%		
TIMING REQUIRE	MENTS: Measurement Mode 1 <sup>(1)</sup>				
T1 <sub>STARTSTOP_Min</sub>	Minimum Time between Start and Stop Signal	12			ns
T1 <sub>STOPSTOP_Min</sub>	Minimum Time between 2 Stop Signals	67			ns
T1 <sub>STARTSTOP_Max</sub>	Maximum time bet. Start and Stop Signal			500	ns
T1 <sub>STOPSTOP_Max</sub>	Maximum time bet. Start and last Stop Signal			500	ns
TIMING REQUIRE	MENTS: Measurement 2 <sup>(1)</sup>				
T2 <sub>STARTSTOP_Min</sub>	Minimum Time between Start and Stop Signal	2×t <sub>CLOCK</sub>			S
T2 <sub>STOPSTOP_Min</sub>	Minimum Time between 2 Stop Signals	2×t <sub>CLOCK</sub>			S
T2 <sub>STARTSTOP_Max</sub>	Maximum time bet. Start and Stop Signal			(2 <sup>16</sup> -2)×t <sub>CLOCK</sub>	S
T2 <sub>STOPSTOP_Max</sub>	Maximum. time bet. Start and last Stop Signal			(2 <sup>16</sup> -2)×t <sub>CLOCK</sub>	S
TIMING REQUIRE	MENTS: ENABLE INPUT				
T <sub>REN</sub>	Rise Time for Enable Signal (20%-80%)		1 to 100	_	ns
T <sub>FEN</sub>	Fall Time for Enable Signal (20%-80%)		1 to 100	·	ns

<sup>(1)</sup> Specified by design.

<sup>(2)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

<sup>(3)</sup> All voltages are with respect to ground, unless otherwise specified.

<sup>(2)</sup> JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



# **Recommended Operating Conditions (continued)**

 $T_A = 25^{\circ}C$  , VDD = 3.3V, GND = 0V (unless otherwise noted).

		MIN NOM	MAX	UNIT
TIMING REQUI	REMENTS: START, STOP, CLOCK			
T <sub>RST</sub> , T <sub>FST</sub>	Maximum rise, fall time for START, STOP signals (20%-80%)	1		ns
T <sub>RXCLK</sub> , T <sub>FXCLK</sub>	Maximum rise, fall time for external CLOCK (20%-80%)	1		ns
TIMING REQUI	REMENTS: TRIGG			
T <sub>TRIGSTART</sub>	Time from TRIG to START	5		ns
TEMPERATUR	E			
T <sub>A</sub>	Ambient temperature	-40	85	°C
TJ	Junction temperature	-40	85	°C

## 7.4 Thermal Information

	THERMAL METRIC <sup>(1)</sup>	TDC7200 PW [TSSOP] 14 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	134.9	
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	63	
$R_{\theta JB}$	Junction-to-board thermal resistance	76.8	°C/W
ΨЈТ	Junction-to-top characterization parameter	12.4	C/VV
ΨЈВ	Junction-to-board characterization parameter	76.2	
$\theta_{JA}$	Package thermal impedance	113	

<sup>(1)</sup> For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.



#### 7.5 Electrical Characteristics

 $T_A = 25^{\circ}\text{C}$ , VDD = 3.3 V, GND = 0 V (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
TDC CH	ARACTERISTICS					
LSB	Resolution	Single shot measurement		55		ps
T <sub>ACC-2</sub>	Accuracy (Mode 2) (1)	CLOCK = 8 MHz		28		ps
_	Standard Daviation (Made 2)	Measured time = 100 μs		50		ps
T <sub>STD-2</sub>	Standard Deviation (Mode 2)	Measured time = 1 μs		35		ps
OUTPU	T CHARACTERISTICS: TRIGG,	INTB, DOUT				
V <sub>OH</sub>	Output voltage high	Isource = -2 mA	2.31	2.95		V
V <sub>OL</sub>	Output voltage low	Isink = 2 mA		0.35	0.99	V
INPUT C	CHARACTERISTICS: ENABLE, S	START, STOP, CLOCK, DIN, CSB,SCLK				
C <sub>in</sub>	Input capacitance (2)			3		pF
POWER	CONSUMPTION (see Measurer	ment Mode 1 and Measurement Mode 2)				
I <sub>sh</sub>	Shutdown current	EN = LOW		0.3	2	μΑ
I <sub>QA</sub>	Quiescent Current A	EN = HIGH; TDC running		1.35		mA
I <sub>QB</sub>	Quiescent Current B	EN = HIGH; TDC OFF, Clock Counter running		71		μA
I <sub>QC</sub>	Quiescent Current C	EN = HIGH; measurement stopped, SPI communication only		87		μΑ
$I_{QD}$	Quiescent Current D	TDC OFF, counter stopped, no communication		50		μΑ

<sup>(1)</sup> Accuracy is defined as the systematic error in the output signal; the error of the device excluding noise.

## 7.6 Timing Requirements

7.0	ig Kequitements	MIN	NOM MAX	UNIT
TIMING REQ	UIREMENTS: START, STOP INPUTS, CLOCK			
PW <sub>START</sub>	Pulse width for Start Signal	10		ns
PW <sub>STOP</sub>	Pulse width for Stop Signal	10		ns
SERIAL INTE	RFACE TIMING CHARACTERISTICS (VDD = 3.3 V, f <sub>SCLK</sub> = 20 MHz	(See Figure 1)		
f <sub>SCLK</sub>	SCLK Frequency		20	MHz
t <sub>1</sub>	SCLK period	50		ns
t <sub>2</sub>	SCLK High Time	16		ns
t <sub>3</sub>	SCLK Low Time	16		ns
t <sub>4</sub>	DIN setup time	4		ns
t <sub>5</sub>	DIN hold time	4		ns
t <sub>6</sub>	CSB fall to SCLK rise	6		ns
t <sub>7</sub>	Last SCLK rising edge to CSB rising edge	6		ns
t <sub>8</sub>	Minimum pause time (CSB high)	40		ns
t <sub>9</sub>	Clk fall to DOUT bus transition		12	ns

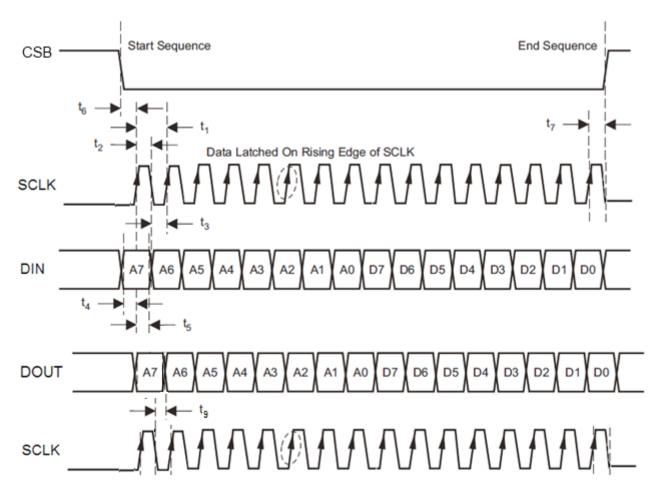
## 7.7 Switching Characteristics

 $T_A = 25^{\circ}C$  , VDD = 3.3 V, GND = 0 V (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	MIN TYP MAX			UNIT
WAKE UP TIME						
T <sub>WAKEUP_PERIOD</sub>	Time to be ready for Measurement	LSB within 0.3% of settled value		300		μs

<sup>(2)</sup> Specified by design.





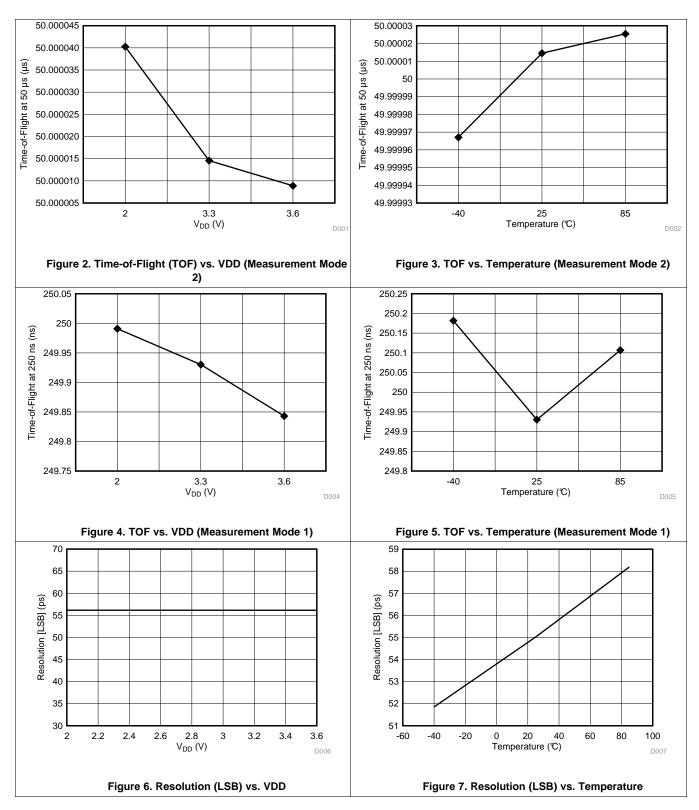
DIN: SCLK rising edge DOUT: SCLK falling edge

Figure 1. SPI Register Write: 8 bit Register Example



#### 7.8 Typical Characteristics

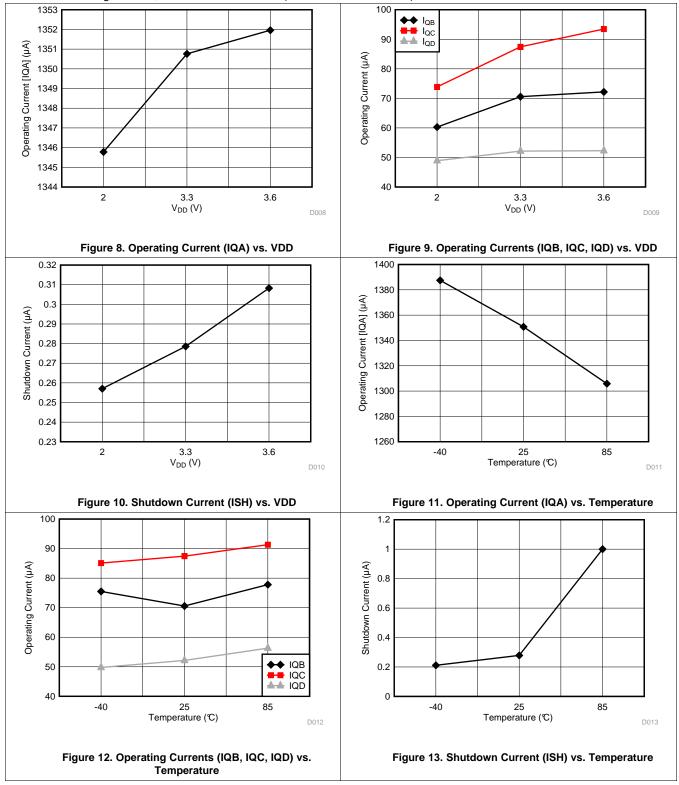
 $T_A = 25^{\circ}\text{C}$ , VDD = 3.3 V, GND = 0 V, CLOCK = 8 MHz, CALIBRATION2\_PERIODS = 10, AVG\_CYCLES = 1 Measurement, NUM\_STOP = Single STOP, Measurement Mode 2 (unless otherwise noted).



# TEXAS INSTRUMENTS

## **Typical Characteristics (continued)**

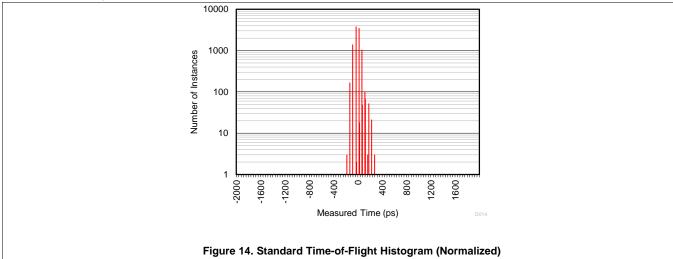
 $T_A = 25^{\circ}\text{C}$ , VDD = 3.3 V, GND = 0 V, CLOCK = 8 MHz, CALIBRATION2\_PERIODS = 10, AVG\_CYCLES = 1 Measurement, NUM\_STOP = Single STOP, Measurement Mode 2 (unless otherwise noted).





## **Typical Characteristics (continued)**

 $T_A = 25^{\circ}C$ , VDD = 3.3 V, GND = 0 V, CLOCK = 8 MHz,  $CALIBRATION2\_PERIODS = 10$ ,  $AVG\_CYCLES = 1$  Measurement,  $NUM\_STOP = Single STOP$ , Measurement Mode 2 (unless otherwise noted).



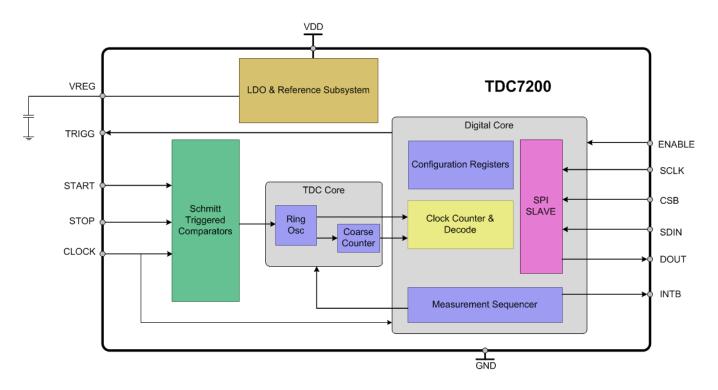


#### 8 Detailed Description

#### 8.1 Overview

The TDC7200 is a stopwatch IC used to measure time between a single event (edge on START pin) and multiple subsequent events (edge on STOP pin). An event from a START pulse to a STOP pulse is also known as time-of-flight, or TOF for short. The device has an internal time base that is used to measure time with accuracy in the order of picoseconds. This accuracy makes the TDC7200 ideal for application such as flow meter, where zero and low flow measurements require high accuracy in the picoseconds range.

#### 8.2 Functional Block Diagram



## 8.3 Feature Description

#### 8.3.1 LDO

The LDO (low-dropout) is an internal supply voltage regulator for the TDC7200. No external circuitry needs to be connected to the output of this regulator other than the mandatory external decoupling capacitor.

Recommendations for the decoupling capacitor parameters:

- · Type: ceramic
- Capacitance: 0.4  $\mu$ F-2.7  $\mu$ F (1  $\mu$ F typical). If using a capacitor value outside the recommended range, the part may malfunction and can be damaged.
- ESR: 100 mΩ (max)



#### **Feature Description (continued)**

#### 8.3.2 CLOCK

TDC7200 needs an external reference clock connected to the CLOCK pin. The external CLOCK is used to calibrate the internal time base accurately and therefore, the measurement accuracy is heavily dependent on the external CLOCK accuracy. This reference clock is also used by all digital circuits inside the device; thus, CLOCK has to be available and stable at all times when the device is enabled (ENABLE = HIGH).

Figure 15 shows the typical effect of the external CLOCK frequency on the measurement uncertainty. With a reference clock of 1MHz, the standard deviation of a set of measurement results is approximately 243ps. As the reference clock frequency is increased, the standard deviation (or measurement uncertainty) reduces. Therefore, using a reference clock of 16MHz is recommended for optimal performance.

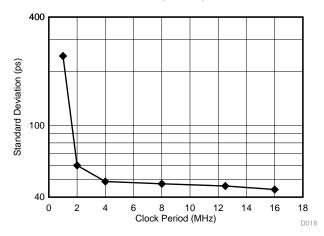


Figure 15. Standard Deviation vs. CLOCK

#### 8.3.3 Counters

#### 8.3.3.1 Coarse and Clock Counters Description

Time measurements by the TDC7200 rely on two counters: the Coarse Counter and the Clock Counter. The Coarse Counter counts the number of times the ring oscillator (the TDC7200's core time measurement mechanism) wraps, which is used to generate the results in the TIME1 to TIME6 registers.

The Clock Counter counts the number of integer clock cycles between START and STOP events and is used in *Measurement Mode 2* only. The results for the Clock Counter are displayed in the CLOCK\_COUNT1 to CLOCK\_COUNT5 registers.

#### 8.3.3.2 Coarse and Clock Counters Overflow

Once the coarse counter value has reached the corresponding value of the Coarse Counter Overflow registers, then its interrupt bit will be set to 1. In other words, if  $(TIMEn / 63) \ge COARSE\_CNTR\_OVF$ , then  $COARSE\_CNTR\_OVF\_INT = 1$  (this interrupt bit is located in the  $INT\_STATUS$  register).  $COARSE\_CNTR\_OVF$  =  $(COARSE\_CNTR\_OVF\_H \times 2^8 + COARSE\_CNTR\_OVF\_L)$ , and TIMEn refers to the TIME1 to TIME6 registers.

Similarly, once the clock counter value has reached the corresponding value of the Clock Counter Overflow registers, then its interrupt bit will be set to 1. In other words, if CLOCK\_COUNTn > CLOCK\_CNTR\_OVF, then CLOCK\_CNTR\_OVF\_INT = 1 (this interrupt bit is located in the INT\_STATUS register). CLOCK\_CNTR\_OVF = (CLOCK\_CNTR\_OVF\_H x 2<sup>8</sup> + CLOCK\_CNTR\_OVF\_L), and CLOCK\_COUNTn refers to the CLOCK\_COUNT1 to CLOCK\_COUNT5 registers.

As soon as there is an overflow detected, the running measurement will be terminated immediately.



#### **Feature Description (continued)**

#### 8.3.3.3 Clock Counter STOP Mask

The value in the Clock Counter STOP Mask registers define the end of the mask window. The Clock Counter STOP Mask value will be referred to as CLOCK\_CNTR\_STOP\_MASK = (CLOCK\_CNTR\_STOP\_MASK\_H x 2<sup>8</sup> + CLOCK\_CNTR\_STOP\_MASK\_L).

The Clock Counter is started by the first rising edge of the external CLOCK after the START signal (see Figure 18). All STOP signals occurring before the value set by the CLOCK\_CNTR\_STOP\_MASK registers will be ignored. This feature can be used to help suppress wrong or unwanted STOP trigger signals.

For example, assume the following values:

- The first time-of-flight (TOF1), which is defined as the time measurement from the START to the 1<sup>st</sup> STOP = 19 μs.
- The second time-of-flight (TOF2), which is defined as the time measurement from the START to the 2<sup>nd</sup> STOP = 119 μs.
- CLOCK = 8 MHz

In this example, the TDC7200 will provide a CLOCK\_COUNT1 of approximately 152 (19  $\mu s$  /  $t_{CLOCK}$ ), and CLOCK\_COUNT2 of approximately 952 (119  $\mu s$  /  $t_{CLOCK}$ ). If the user sets CLOCK\_CNTR\_STOP\_MASK anywhere between 152 and 952, then the 1<sup>st</sup> STOP will be ignored and 2<sup>nd</sup> STOP will be measured.

The Clock Counter Overflow value (CLOCK\_CNTR\_OVF\_H x 2<sup>8</sup> + CLOCK\_CNTR\_OVF\_L) should always be higher than the Clock Counter STOP Mask value (x 2<sup>8</sup> + CLOCK\_CNTR\_STOP\_MASK\_L). Otherwise, the Clock Counter Overflow Interrupt will be set before the STOP mask time expires, and the measurement will be halted.

#### 8.3.3.4 ENABLE

The ENABLE pin is used as a reset to all digital circuits in the TDC7200. Therefore, it is essential that the ENABLE pin sees a positive edge after the device has powered up. It is also important to ensure that there are no transients (glitches, etc.) on the ENABLE pin; such glitches could cause the device to RESET.

#### 8.4 Device Functional Modes

#### 8.4.1 Calibration

The time measurements performed by the TDC7200 are based on an internal time base which is represented as the LSB value of the TIME1 to TIME6 results registers. The typical LSB value can be seen in *Electrical Characteristics*. However, the actual value of the LSB can vary depending on environmental variables (temperature, systematic noise, etc.). This variation can introduce significant error into the measurement result. There is also an offset error in the measurement due to certain internal delays in the device.

In order to compensate for these errors and to calculate the actual LSB value, calibration needs to be performed. The TDC7200 calibration consists of two measurement cycles of the external CLOCK. The first is a measurement of a single clock cycle period of the external clock; the second measurement is for the number of external CLOCK periods set by the CALIBRATION2\_PERDIOS in the CONFIG2 register. The results from the calibration measurements are stored in the CALIBRATION1 and CALIBRATION2 registers.

The two-point calibration is used to determine the actual LSB in real time in order to convert the TIME1 to TIME6 results from number of delays to a real time-of-flight (TOF) number. As discussed in the next sections, the calibrations will be used for calculating time-of-flight (TOF) in measurement modes 1 and 2.



#### 8.4.2 Measurement Modes

#### 8.4.2.1 Measurement Mode 1

In measurement mode 1 as shown in Figure 16, the TDC7200 performs the entire counting from START to the last STOP using its internal ring oscillator plus coarse counter. This method is recommended for measuring shorter time durations of < 500 ns. Using measurement mode 1 for measuring time > 500ns decreases accuracy of the measurement (as shown in Figure 17), and is not recommended.

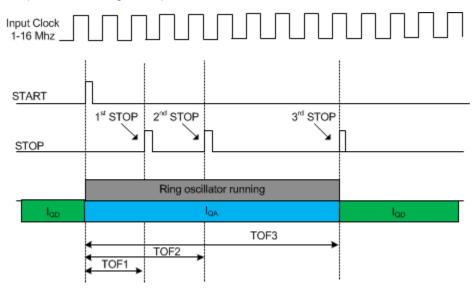


Figure 16. Measurement Mode 1

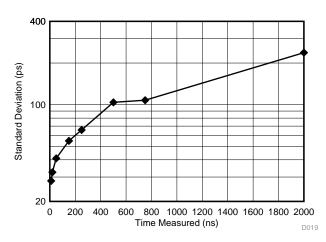


Figure 17. Measurement Mode 1 Standard Deviation vs. Measured Time-of-Flight



#### 8.4.2.1.1 Calculating Time-of-Flight (Measurement Mode 1)

For measurement mode 1, the time-of-flight (TOF) between the START to the n<sup>th</sup> STOP can be calculated using Equation 1:

$$\begin{split} TOF_n &= (TIME_n)(normLSB) \\ normLSB &= \frac{(CLOCKperiod)}{(calCount)} \\ calCount &= \frac{CALIBRATION2 - CALIBRATION1}{(CALIBRATION2 \_PERIODS) - 1} \end{split}$$

#### where

- TOF<sub>n</sub> [sec] = time-of-flight measurement from the START to the n<sup>th</sup> STOP
- TIME<sub>n</sub> = n<sup>th</sup> TIME measurement given by the TIME1 to TIME6 registers
- normLSB [sec] = normalized LSB value from calibration
- CLOCKperiod [sec] = external CLOCK period
- CALIBRATION1 [count] = TDC count for first calibration cycle
- CALIBRATION2 [count] = TDC count for second calibration cycle
- CALIBRATION2 PERIODS = setting for the second calibration cycle; located in register CONFIG2 (1)

For example, assume the time-of-flight between the START to the 1<sup>st</sup> STOP is desired, and the following readouts were obtained:

- CALIBRATION2 = 21121 (decimal)
- CALIBRATION1 = 2110 (decimal)
- CALIBRATION2 PERIODS = 10
- CLOCK = 8MHz
- TIME1 = 4175 (decimal)

Therefore, the calculation for time-of-flight is:

- calCount = (21121 2110) / (10 1) = 2112.33
- normLSB = (1/8MHz) / (2112.33) = 5.917 x 10<sup>-11</sup>
- TOF1 = (4175)(5.917 x 10<sup>-11</sup>) = 247.061 ns

#### 8.4.2.2 Measurement Mode 2

In measurement mode 2, the internal ring oscillator of the TDC7200 is used only to count fractional parts of the total measured time. As shown in Figure 18, the internal ring oscillator starts counting from when it receives the START signal until the first rising edge of the CLOCK. Then, the internal ring oscillator switches off, and the Clock counter starts counting the clock cycles of the external CLOCK input until a STOP pulse is received. The internal ring oscillator again starts counting from the STOP signal until the next rising edge of the CLOCK.



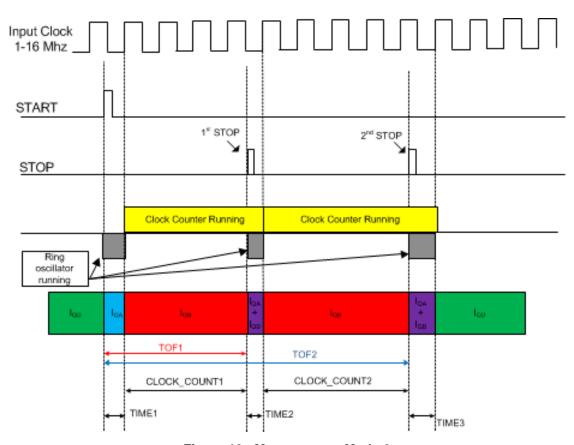


Figure 18. Measurement Mode 2

(2)



## **Device Functional Modes (continued)**

#### 8.4.2.2.1 Calculating Time-of-Flight (TOF) (Measurement Mode 2)

The time-of-flight (TOF) between the START to the n<sup>th</sup> STOP can be calculated using Equation 2:

$$\begin{split} TOF_n &= normLSB(TIME1-TIME_{n+1}) + (CLOCK\_COUNT_n)(CLOCKperiod) \\ normLSB &= \frac{(CLOCKperiod)}{(calCount)} \\ calCount &= \frac{CALIBRATION2 - CALIBRATION1}{(CALIBRATION2\_PERIODS) - 1} \\ offset &= CLOCKperiod - (CALIBRATION1)(normLSB) \end{split}$$

#### where

- TOF<sub>n</sub> [sec] = time-of-flight measurement from the START to the n<sup>th</sup> STOP
- TIME1 = time 1 measurement given by the TDC7200 register address 0x10
- TIME<sub>(n+1)</sub> = (n+1) time measurement, where n = 1 to 5 (TIME2 to TIME6 registers)
- normLSB [sec] = normalized LSB value from calibration
- CLOCK\_COUNT<sub>n</sub> = nth clock count, where n = 1 to 5 (CLOCK\_COUNT1 to CLOCK\_COUNT5)
- CLOCKperiod [sec] = external CLOCK period
- CALIBRATION1 [count] = TDC count for first calibration cycle
- CALIBRATION2 [count] = TDC count for second calibration cycle
- CALIBRATION2\_PERIODS = setting for the second calibration; located in register CONFIG2

For example, assume the time-of-flight between the START to the 1<sup>st</sup> STOP is desired, and the following readouts were obtained:

- CALIBRATION2 = 23133 (decimal)
- CALIBRATION1 = 2315 (decimal)
- CALIBRATION2 PERIODS = 10
- CLOCK = 8MHz
- TIME1 = 2147 (decimal)
- TIME2 = 201 (decimal)
- CLOCK\_COUNT1 = 3818 (decimal)

Therefore, the calculation for time-of-flight is:

$$calCount = \frac{CALIBRATION2 - CALIBRATION1}{(CALIBRATION2\_PERIODS) - 1} = \frac{(23133 - 2315)}{(10 - 1)} = 2313.11$$
 
$$normLSB = \frac{(CLOCKperiod)}{(calCount)} = \frac{(1/8MHz)}{2313.11} = 5.40 * 10^{-11}$$
 
$$TOF1 = (TIME1)(normLSB) + (CLOCK\_COUNT1)(CLOCKperiod) - (TIME2)(normLSB)$$
 
$$TOF1 = (2147) \left(5.40 * 10^{-11}\right) + (318)(1/8MHz) - (201)(5.40 * 10^{-11})$$
 
$$TOF1 = 39.855 \mu s$$
 (3)



#### 8.4.3 Timeout

For one STOP, the TDC performs the measurement by counting from the START signal to the STOP signal. If no STOP signal is received, either the Clock Counter or Coarse Counter will overflow and will generate an interrupt (see *Coarse and Clock Counters Overflow*). If no START signal is received, the timer waits indefinitely for a START signal to arrive.

For multiple STOPs, the TDC performs the measurement by counting from the START signal to the last STOP signal. All earlier STOP signals are captured and stored into the corresponding Measurement Results registers (TIME1 to TIME6, CLOCK\_COUNT1 to CLOCK\_COUNT5, CALIBRATION1, CALIBRATION2). The minimum time required between two consecutive STOP signals is defined in the *Recommended Operating Conditions* table. The device can be programmed to measure up to 5 STOP signals by setting the NUM\_STOP bits in the CONFIG2 register.

#### 8.4.4 Multi-Cycle Averaging

In the Multi-Cycle Averaging Mode, the TDC7200 will perform a series of measurements on its own and will only send an interrupt to the MCU (for example, MSP430, C2000, etc) for wake up after the series has been completed. While waiting, the MCU can remain in sleep mode during the whole cycle (as shown in Figure 19).

Multi-Cycle Averaging Mode Setup and Conditions:

- The number of averaging cycles should be selected (1 to 128). This is done by programming the AVG\_CYCLES bit in the CONFIG2 register.
- The results of all measurements are reported in the Measurement Results registers (TIME1 to TIME6, CLOCK\_COUNT1 to CLOCK\_COUNT5, CALIBRATION1, CALIBRATION2 registers). The CLOCK\_COUNTn registers should be right shifted by the log2(AVG\_CYCLES) before calculating the time-of-flight (TOF). For example, if using the multi-cycle averaging mode, Equation 2 should be rewritten as: TOFn = normLSB [TIME1 TIME(n+1)] + [CLOCK\_COUNTn >> log 2 (AVG\_CYCLES)] x [CLOCKperiod]
- Following each average cycle, the TDC generates either a trigger event on the TRIGG pin after the calibration
  measurement to commence a new measurement or an interrupt on the INTB pin, indicating that the averaging
  sequence has completed.

This mode allows multiple measurements without MCU interaction, thus optimizing power consumption for the overall system.

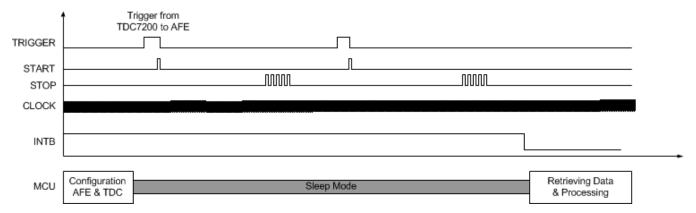


Figure 19. Multi-Cycle Averaging Mode Example with 2 Averaging Cycles and 5 STOP Signals

#### 8.4.5 START and STOP Edge Polarity

In order to achieve the highest measurement accuracy, having the same edge polarity for the START and STOP input signals is highly recommended. Otherwise, slightly different propagation delays due to symmetry shift between the rising and falling edge configuration will impact the measurement accuracy.

For highest measurement accuracy in measurement mode 2, it's strongly recommended to choose for the START and STOP signal the "rising edge". This is done by setting the START\_EDGE and STOP\_EDGE bits in the CONFIG1 register to 0.



## 8.4.6 Measurement Sequence

The TDC7200 is a stopwatch IC that measures time between a START and multiple STOP events. The measurement sequence of the TDC7200 is as follows:

- 1. After powering up the device, the EN pin needs to be low. There is one low to high transition required while VDD is supplied for correct initialization of the device.
- 2. MCU software requests a new measurement to be initiated via the SPI™ interface.
- 3. After the start new measurement bit START\_MEAS has been set in the CONFIG1 register, the TDC7200 generates a trigger signal on the TRIGG pin, which is typically used by the corresponding ultrasonic analog-front-end (such as the TDC1000) as start trigger for a measurement (for example, transmit signal for the ultrasonic burst)
- 4. Immediately after sending the trigger, the TDC7200 enables the START pin and waits to receive the START pulse edge
- 5. After receiving a START, the TDC resets the TRIGG pin
- The Clock counter is started after the next rising edge of the external clock signal (Measurement Mode 2).
   The Clock Counter STOP Mask registers (CLOCK\_CNTR\_STOP\_MASK\_H and CLOCK\_CNTR\_STOP\_MASK\_L) determine the length of the STOP mask window.
- 7. After reaching the Clock Counter STOP Mask value, the STOP pin waits to receive a single or multiple STOP trigger signal from the analog-front-end (for example, detected echo signal of the ultrasonic burst signal)
- 8. After the last STOP trigger has been received, the TDC will signal to the MCU via interrupt (INTB pin) that there are new measurement results waiting in the registers. START, STOP and TRIGG pin are disabled (in Multi-Cycle Averaging Mode, the TDC will start the next cycle automatically by generating a new TRIGG signal). Note: INTB must be utilized to determine TDC measurement completion; polling the INT\_STATUS register to determine measurement completion is NOT recommended as it will interfere with the TDC measurement.
- After the results are retrieved, the MCU can then start a new measurement with the same register settings. This is done by just setting the START measurement bit via SPI. It is not required to drive the ENABLE pin low between measurements.
- 10. The ENABLE pin can be taken low, if the time duration between measurements is long, and it is desired to put the TDC7200 in its lowest power state. However, upon taking ENABLE high again, the device will come up with its default register settings and will need to be configured via SPI.

#### 8.4.7 Wait Times for TDC7200 Startup

The required wait time following the rising edge of the ENABLE pin of the TDC7200 is defined by three key times, as shown in Figure 20. All three times relate to the startup of the TDC7200's internal LDO, which is power gated when the device is disabled for optimal power consumption. The first parameter, T1<sub>SPl\_RDY</sub>, is the time after which the SPI interface is accessible. The second (T2<sub>LDO\_SET1</sub>) parameter and third (T3<sub>LDO\_SET2</sub>) parameter are related to the performance of a measurement made while the internal LDO is settling. The LDO supplies the TDC7200's time measurement device, and a change in voltage on its supply during a measurement translates directly to an inaccuracy. It is therefore recommended to wait until the LDO is settled before time measurement begins.

The first time period relating to the measurement accuracy is  $T2_{LDO\_SET1}$ , the LDO settling time 1. This is the time after which the LDO has settled to within 0.3% of its final value. A 0.3% error translates to a worst case time error (due to the LDO settling) of 0.3% x  $t_{CLOCK}$ , which is 375ps in the case of an 8MHz reference clock, or 187.5ps if a 16MHz clock is used. Finally, the time  $T3_{LDO\_SET2}$  is the time after which the LDO has settled to its final value. For best performance, it is recommended that a time measurement is not started before  $T3_{LDO\_SET2}$  to allow the LDO to fully settle. Typical times for  $T1_{SPl\_RDY}$  is 100  $\mu$ s, for  $T2_{LDO\_SET1}$  is 300  $\mu$ s, and for  $T3_{LDO\_SET2}$  is 1.5 ms.



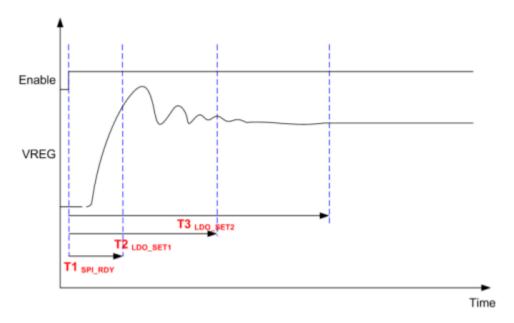


Figure 20. VREG Startup Time

#### 8.5 Programming

#### 8.5.1 Serial Peripheral Interface (SPI)

The serial interface consists of data input (DIN), data output (DOUT), serial interface clock (SCLK), and chip select bar (CSB). The serial interface is used to configure the TDC7200 parameters available in various configuration registers.

The communication on the SPI bus supports write and read transactions. A write transaction consists of a single write command byte, followed by single data byte. A read transaction consists of a single read command byte followed by 8 or 24 SCLK cycles. The write and read command bytes consist of a 1-bit auto-increment bit, a 1-bit read or write instruction, and a 6-bit register address. Figure 21 shows the SPI protocol for a transaction involving one byte of data (read or write).



#### **Programming (continued)**

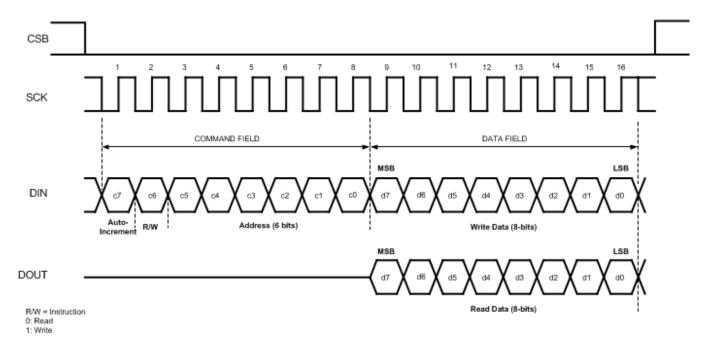


Figure 21. SPI Protocol

#### 8.5.1.1 CSB

CSB is an active-low signal and needs to be low throughout a transaction. That is, CSB should not pulse between the command byte and the data byte of a single transaction.

De-asserting CSB always terminates an ongoing transaction, even if it is not yet complete. Re-asserting CSB will always bring the device into a state ready for the next transaction, regardless of the termination status of a previous transaction.

#### 8.5.1.2 SCLK

SPI clock can idle high or low. It is recommended to keep SCLK as clean as possible to prevent glitches from corrupting the SPI frame.

#### 8.5.1.3 DIN

Data In (DIN) is driven by the SPI master by sending the command and the data byte to configure the TDC7200.

#### 8.5.1.4 DOUT

Data Out (DOUT) is driven by the TDC7200 when the SPI master initiates a read transaction. When the TDC7200 is not being read out, the DOUT pin is in high impedance mode and is undriven.



#### **Programming (continued)**

#### 8.5.1.5 Register Read/Write

Access to the internal registers can be done through the serial interface formed by pins CSB (Chip Select - active low), SCLK (serial interface clock), DIN (data input), and DOUT (data out).

Serial shift of bits into the device is enabled when CSB is low. Serial data DIN is latched (MSB received first, LSB received last) at every rising edge of SCLK when CSB is active (low). The serial data is loaded into the register with the last data bit SCLK rising edge when CSB is low. In the case that the word length exceeds the register size, the excess bits are ignored. The interface can work with SCLK frequency from 20MHz down to very low speeds (a few Hertz) and even with a non-50% duty-cycle SCLK.

The SPI transaction is divided in two main portions:

- · Address and Control: Auto Increment Mode selection bit, Read/Write bit, Address 6 bits
- Data: 8 bit or 24 bit

When writing to a register with unused bits, these should be set to 0.

	Address and Control (A7 - A0)									
A7	A6	A5	A5 A4 A3 A2 A1 A0							
Auto Increment	RW		Register Address							
0: OFF 1: ON	Read = 0 Write = 1		00 h up to 3Fh							

#### 8.5.1.6 Auto Increment Mode

When the Auto Increment Mode is OFF, only the register indicated by the Register Address will be accessed, all cycles beyond the register length will be ignored. When the Auto Increment is ON, the register of the Register Address is accessed first, then without interruption, subsequent registers are accessed.

The Auto Increment Mode can be either used to access the configuration (CONFIG1 and CONFIG2) and status (INT\_STATUS) registers, or for the Measurement Results registers (TIME1 to TIME6, CLOCK\_COUNT1 to CLOCK\_COUNT5, CALIBRATION1, CALIBRATION2). As both register block use registers with different length, it's not possible to access all registers of the device within one single access cycle.



## 8.6 Register Maps

## 8.6.1 Register Initialization

After power up (VDD supplied, ENABLE Pin low to high transition) the internal registers are initialized with the default value. Disabling the part by pulling ENABLE pin to GND will set the device into total shutdown. As the internal LDO is turned off settings in the register will be lost. The device initializes the registers with default values with the next enable (ENABLE pin to VDD).

**Table 1. Register Summary** 

REGISTER ADDRESS	REGISTER NAME	REGISTER DESCRIPTION	SIZE (BITS)	RESET VALUE
00h	CONFIG1	Configuration Register 1	8	00h
01h	CONFIG2	Configuration Register 2	8	40h
02h	INT_STATUS	Interrupt Status Register	8	00h
03h	INT_MASK	Interrupt Mask Register	8	07h
04h	COARSE_CNTR_OVF_H	Coarse Counter Overflow Value High	8	FFh
05h	COARSE_CNTR_OVF_L	Coarse Counter Overflow Value Low	8	FFh
06h	CLOCK_CNTR_OVF_H	CLOCK Counter Overflow Value High	8	FFh
07h	CLOCK_CNTR_OVF_L	CLOCK Counter Overflow Value Low	8	FFh
08h	CLOCK_CNTR_STOP_MASK_H	CLOCK Counter STOP Mask High	8	00h
09h	CLOCK_CNTR_STOP_MASK_L	CLOCK Counter STOP Mask Low	8	00h
10h	TIME1	Measured Time 1	24	00_0000h
11h	CLOCK_COUNT1	CLOCK Counter Value	24	00_0000h
12h	TIME2	Measured Time 2	24	00_0000h
13h	CLOCK_COUNT2	CLOCK Counter Value	24	00_0000h
14h	TIME3	Measured Time 3	24	00_0000h
15h	CLOCK_COUNT3	CLOCK Counter Value	24	00_0000h
16h	TIME4	Measured Time 4	24	00_0000h
17h	CLOCK_COUNT4	CLOCK Counter Value	24	00_0000h
18h	TIME5	Measured Time 5	24	00_0000h
19h	CLOCK_COUNT5	CLOCK Counter Value	24	00_0000h
1Ah	TIME6	Measured Time 6	24	00_0000h
1Bh	CALIBRATION1	Calibration 1, 1 CLOCK Period	24	00_0000h
1Ch	CALIBRATION2	Calibration 2, 2/10/20/40 CLOCK Periods	24	00_000h



# 8.6.2 CONFIG1: Configuration Register 1 R/W (address = 00h) [reset = 0h]

# Figure 22. Configuration Register 1

7	6	5	4	3	2	1	0
FORCE_CAL	PARITY_EN	TRIGG_EDGE	STOP_EDGE	START_EDGE	MEAS_MODE		START_MEAS
R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

# **Table 2. Configuration Register 1 Field Descriptions**

Bit	Field	Туре	Reset	Description
7	FORCE_CAL	R/W	0	0: Calibration is not performed after interrupted measurement (for example, due to counter overflow or missing STOP signal)
				1: Calibration is always performed at the end (for example, after a counter overflow)
6	PARITY_EN	R/W	0	0: Parity bit for Measurement Result Registers* disabled (Parity Bit always 0)
				1: Parity bit for Measurement Result Registers enabled (Even Parity)
				*The Measurement Results registers are the TIME1 to TIME6, CLOCK_COUNT1 to CLOCK_COUNT5, CALIBRATION1, CALIBRATION2 registers.
5	TRIGG_EDGE	R/W	0	0: TRIGG is output as a Rising edge signal
				1: TRIGG is output as a Falling edge signal
4	STOP_EDGE	R/W	0	0: Measurement is stopped on Rising edge of STOP signal
				1: Measurement is stopped on Falling edge of STOP signal
3	START_EDGE	R/W	0	0: Measurement is started on Rising edge of START signal
				1: Measurement is started on Falling edge of START signal
[2:1]	MEAS_MODE	R/W	00h	00: Measurement Mode 1 (for expected time-of-flight < 500 ns).
				01: Measurement Mode 2 (recommended)
				10, 11: Reserved for future functionality
0	START_MEAS	R/W	0	Start New Measurement:
				This bit is cleared when Measurement is Completed.
				0: No effect
				1: Start New Measurement. Writing a 1 will clear all bits in the Interrupt Status Register and Start the measurement (by generating an TRIGG signal) and will reset the content of all Measurement Results registers (TIME1 to TIME6, CLOCK_COUNT1 to CLOCK_COUNT5, CALIBRATION1, CALIBRATION2) to 0.



# 8.6.3 CONFIG2: Configuration Register 2 R/W (address = 01h) [reset = 40h]

# Figure 23. Configuration Register 2

7	6	5 4		3	2	1	0
CALIBRATIO	CALIBRATION2_PERIODS AVG_CYCLES					NUM_STOP	
R/W-0h	R/W-1h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

# **Table 3. Configuration Register 2 Field Descriptions**

Bit	Field	Туре	Reset	Description
[7:6]	CALIBRATION2_PERI ODS	R/W	01h	00: Calibration 2 - measuring 2 CLOCK periods 01: Calibration 2 - measuring 10 CLOCK periods 10: Calibration 2 - measuring 20 CLOCK periods 11: Calibration 2 - measuring 40 CLOCK periods
[5:3]	AVG_CYCLES	R/W	00h	000: 1 Measurement Cycle only (no Multi-Cycle Averaging Mode) 001: 2 Measurement Cycles 010: 4 Measurement Cycles 011: 8 Measurement Cycles 100: 16 Measurement Cycles 101: 32 Measurement Cycles 110: 64 Measurement Cycles 111: 128 Measurement Cycles
[2:0]	NUM_STOP	R/W	00h	000: Single Stop 001: Two Stops 010: Three Stops 011: Four Stops 100: Five Stops 101, 110, 111: No Effect. Single Stop



## 8.6.4 INT\_STATUS: Interrupt Status Register (address = 02h) [reset = 00h]

# Figure 24. Interrupt Status Register

7	6	5	4	3	2	1	0
Reserve d	Reserve d	Reserve d	MEAS_COMPLET E_FLAG	MEAS_STARTED_FL AG	CLOCK_CNT R_ OVF_INT	COARSE_CNTR_ OVF_INT	NEW_MEAS_ INT
R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

## **Table 4. Interrupt Status Register Field Descriptions**

Bit	Field	Туре	Reset	Description	
7	Reserved	R/W	0h		
6	Reserved	R/W	0h		
5	Reserved	R/W	0h		
4	MEAS_COMPLETE_FLAG	R/W	Writing a 1 will clear the status 0: Measurement has not completed		
				Measurement has completed (same information as NEW_MEAS_INT)	
3	MEAS_STARTED_FLAG	R/W	Oh	Writing a 1 will clear the status 0: Measurement has not started 1: Measurement has started (START signal received)	
2	CLOCK_CNTR_OVF_INT	R/W	Oh	Requires writing a 1 to clear interrupt status 0: No overflow detected 1: Clock overflow detected, running measurement will be stopped immediately	
1	COARSE_CNTR_OVF_INT	R/W	Oh	Requires writing a 1 to clear interrupt status 0: No overflow detected 1: Coarse overflow detected, running measurement will be stopped immediately	
0	NEW_MEAS_INT	R/W	Oh	Requires writing a 1 to clear interrupt status 0: Interrupt not detected 1: Interrupt detected – New Measurement has been completed	



## 8.6.5 INT\_MASK: Interrupt Mask Register R/W (address = 03h) [reset = 07h]

#### Figure 25. Interrupt Mask Register

7	6	5	4	3	2	1	0
Reserve	Reserve	Reserve	Reserve	Reserve	CLOCK_CNTR _OVF_MASK	COARSE_CNT R _OVF_MASK	NEW_MEAS _MASK
R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-1h	R/W-1h	R/W-1h

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

## **Table 5. Interrupt Mask Register Field Descriptions**

Bit	Field	Туре	Reset	Description
7	Reserve	R/W	0	
6	Reserve	R/W	0	
5	Reserve	R/W	0	
4	Reserve	R/W	0	
3	Reserve	R/W	0	
2	CLOCK_CNTR_OVF_MASK	R/W	1	CLOCK Counter Overflow Interrupt disabled     CLOCK Counter Overflow Interrupt enabled
1	COARSE_CNTR_OVF_MASK	R/W	1	Coarse Counter Overflow Interrupt disabled     Coarse Counter Overflow Interrupt enabled
0	NEW_MEAS_MASK	R/W	1	New Measurement Interrupt disabled     New Measurement Interrupt enabled

A disabled interrupt will no longer be visible on the device pin (INTB). The interrupt bit in the INT\_STATUS register will still be active.

# 8.6.6 COARSE\_CNTR\_OVF\_H: Coarse Counter Overflow High Value Register (address = 04h) [reset = FFh]

Figure 26. Coarse Counter Overflow Value\_H Register

7	6	5	4	3	2	1	0		
	COARSE_CNTR_OVF_H								
R/W-1h R/W-1h R/W-1h R/W-1h R/W-1h R/W-1h									

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### Table 6. Coarse Counter Overflow Value\_H Register Field Descriptions

Bit	Field	Туре	Reset	Description
7-0	COARSE_CNTR_OVF_H	R/W	FFh	Coarse Counter Overflow Value, upper 8 Bit



# 8.6.7 COARSE\_CNTR\_OVF\_L: Coarse Counter Overflow Low Value Register (address = 05h) [reset = FFh ]

Figure 27. Coarse Counter Overflow Value\_L Register

7	6	5	4	3	2	1	0							
	COARSE_CNTR_OVF_L													
R/W-1h	R/W-1h	R/W-1h	R/W-1h	R/W-1h	R/W-1h	R/W-1h	R/W-1h							

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### Table 7. Coarse Counter Overflow Value\_L Register Field Descriptions

Bit	Field	Туре	Reset	Description
7-0	COARSE_CNTR_OVF_L	R/W	FFh	Coarse Counter Overflow Value, lower 8 Bit
				Note: Don't set COARSE_CNTR_OVF_L to 1.

## 8.6.8 CLOCK\_CNTR\_OVF\_H: Clock Counter Overflow High Register (address = 06h) [reset = FFh]

#### Figure 28. CLOCK Counter Overflow Value\_H Register

7	6	5	4	3	2	1	0							
	CLOCK_CNTR_OVF_H													
R/W-1h R/W-1h R/W-1h R/W-1h R/W-1h R/W-1h														

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### Table 8. CLOCK Counter Overflow Value H Register Field Descriptions

Bit	Field	Туре	Reset	Description
7-0	CLOCK_CNTR_OVF_H	R/W	FFh	CLOCK Counter Overflow Value, upper 8 Bit

#### 8.6.9 CLOCK\_CNTR\_OVF\_L: Clock Counter Overflow Low Register (address = 07h) [reset = FFh]

#### Figure 29. CLOCK Counter Overflow Value\_L Register

7	6	5	4	3	2	1	0							
	CLOCK_CNTR_OVF_L													
R/W-1h R/W-1h R/W-1h R/W-1h R/W-1h R/W-1h														

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### Table 9. CLOCK Counter Overflow Value\_L Register Field Descriptions

Bit	Field	Туре	Reset	Description
7-0	CLOCK_CNTR_OVF_L	R/W	FFh	CLOCK Counter Overflow Value, lower 8 Bit



# 8.6.10 CLOCK\_CNTR\_STOP\_MASK\_H: CLOCK Counter STOP Mask High Value Register (address = 08h) [reset = 00h]

#### Figure 30. CLOCK Counter STOP Mask\_H Register

7	6	5	4	3	2	1	0							
	CLOCK_CNTR_STOP_MASK_H													
R/W-0h R/W-0h R/W-0h R/W-0h R/W-0h R/W-0h R/W-0h														

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### Table 10. CLOCK Counter STOP Mask\_H Register Field Descriptions

Bit	Field	Туре	Reset	Description
7-0	CLOCK_CNTR_STOP_MASK_H	R/W	0	CLOCK Counter STOP Mask, upper 8 Bit

# 8.6.11 CLOCK\_CNTR\_STOP\_MASK\_L: CLOCK Counter STOP Mask Low Value Register (address = 09h) [reset = 00h]

#### Figure 31. CLOCK Counter STOP Mask\_L Register

7	6	5	4	3	2	1	0							
	CLOCK_CNTR_STOP_MASK_L													
R/W-0h	R/W-0h R/W-0h R/W-0h R/W-0h R/W-0h R/W-0h													

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### Table 11. CLOCK Counter STOP Mask L Register Field Descriptions

Bit	Field	Туре	Reset	Description
7-0	CLOCK_CNTR_STOP_MASK_L	R/W	0	CLOCK Counter STOP Mask, lower 8 Bit

#### 8.6.12 TIME1: Time 1 Register (address: 10h) [reset = 00\_0000h]

#### Figure 32. TIME1 Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit	ty Bit Measurement Result: 23 bit integer value (Bit 22: MSB, Bit 0: LSB)																						
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### Table 12. TIME1 Register Field Descriptions

Bit	Field	Туре	Reset	Description
23	Parity Bit	R	0	Parity Bit
22-0	Measurement Result: 23 bit integer value (Bit 22: MSB, Bit 0: LSB)	R	0	Measurement Result



## 8.6.13 CLOCK\_COUNT1: Clock Count Register (address: 11h) [reset = 00\_0000h]

#### Figure 33. CLOCK Count Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit													С	LOC	(_CO	UNT1	Resu	ılt					
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### Table 13. CLOCK\_COUNT1 Register Field Descriptions

Bit	Field	Туре	Reset	Description
23	Parity Bit	R	0	Parity Bit
22-16	Not Used	R	0	These bits will be used in Multi-Cycle Averaging Mode in order to allow higher averaging results.
15-0	CLOCK_COUNT1 Measurement Result	R	0	CLOCK_COUNT1 Measurement Result

## 8.6.14 TIME2: Time 2 Register (address: 12h) [reset = 00\_0000h]

#### Figure 34. TIME2 Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit						М	easure	ement	Resu	ılt: 23	bit int	eger	value	(Bit 2	2: MS	B, Bit	0: LS	B)					
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### **Table 14. TIME2 Register Field Descriptions**

	Bit	Field	Туре	Reset	Description
	23	Parity Bit	R	0	Parity Bit
ſ	22-0	Measurement Result	R	0	Measurement Result

## 8.6.15 CLOCK\_COUNT2: Clock Count Register (address: 13h) [reset = 00\_0000h]

## Figure 35. CLOCK\_COUNT2 Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit														CLO	OCK_	COU	NT2						
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

## Table 15. CLOCK\_COUNT2 Register Field Descriptions

Bit	Field	Туре	Reset	Description
23	Parity bit	R	0	Parity Bit
22-16	Not Used	R	0	These bits will be used in Multi-Cycle Averaging Mode in order to allow higher averaging results.
15-0	CLOCK_COUNT2 result	R	0	CLOCK_COUNT2 result



## 8.6.16 TIME3: Time 3 Register (address: 14h) [reset = 00\_0000h]

#### Figure 36. TIME3 Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit						М	easure	ement	Resu	ılt: 23	bit int	eger	value	(Bit 2	2: MS	B, Bit	0: LS	B)					
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### **Table 16. TIME3 Register Field Descriptions**

	Bit	Field	Туре	Reset	Description
	23	Parity bit	R	0	Parity Bit
Ī	22-0	Measurement result	R	0	Measurement Result

## 8.6.17 CLOCK\_COUNT3: Clock Count Registers (address: 15h) [reset = 00\_0000h]

## Figure 37. CLOCK\_COUNT3 Count Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit														CLO	OCK_	COU	NT3						
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

## Table 17. CLOCK\_COUNT3 Register Field Descriptions

Bit	Field	Туре	Reset	Description
23	Parity bit	R	0	Parity bit
22-16	Not Used	R	0	These bits will be used in Multi-Cycle Averaging Mode in order to allow higher averaging results.
15-0	CLOCK_COUNT3 Result	R	0	CLOCK_COUNT3 Result

## 8.6.18 TIME4: Time 4 Register (address: 16h) [reset = 00\_0000h]

## Figure 38. TIME4 Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit						М	easure	ement	Resu	ılt: 23	bit int	eger	value	(Bit 2	2: MS	B, Bit	0: LS	B)					
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### **Table 18. TIME4 Register Field Descriptions**

Bit	Field	Туре	Reset	Description
23	Parity bit	R	0	
22-0	Measurement result	R	0	Measurement result



## 8.6.19 CLOCK\_COUNT4: Clock Count Register (address: 17h) [reset = 00\_0000h]

#### Figure 39. CLOCK\_COUNT4 Count Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit														CL	OCK_	COU	NT4						
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### Table 19. CLOCK\_COUNT4 Register Field Descriptions

Bit	Field	Туре	Reset	Description
23	Parity bit	R	0	Parity bit
22-16	Not Used	R	0	These bits will be used in Multi-Cycle Averaging Mode in order to allow higher averaging results.
15-0	CLOCK_COUNT4 Result	R	0	CLOCK_COUNT4 Result

## 8.6.20 TIME5: Time 5 Register (address: 18h) [reset = 00\_0000h]

## Figure 40. TIME5 Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit						М	easure	ement	Resu	ılt: 23	bit int	eger	value	(Bit 2	2: MS	B, Bit	0: LS	B)					
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

## **Table 20. TIME5 Register Field Descriptions**

Bit	Field	Туре	Reset	Description
23	Parity bit	R	0	Parity Bit
22-0	Measurement result	R	0	Measurement result

## 8.6.21 CLOCK\_COUNT5: Clock Count Register (address: 19h) [reset = 00\_0000h]

## Figure 41. CLOCK\_COUNT5 Count Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit														CLO	OCK_	COU	NT5						
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

#### Table 21. CLOCK\_COUNT5 Register Field Descriptions

Bit	Field	Туре	Reset	Description
23	Parity bit	R	0	Parity bit
22-16	Not Used	R	0	These bits will be used in Multi-Cycle Averaging Mode in order to allow higher averaging results.
15-0	CLOCK_COUNT5 Result	R	0	CLOCK_COUNT5 Result



## 8.6.22 TIME6: Time 6 Register (address: 1Ah) [reset = 00\_0000h]

## Figure 42. TIME6 Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit						М	easure	ement	Resu	ılt: 23	bit int	eger	value	(Bit 2	2: MS	B, Bit	0: LS	B)					
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

## Table 22. TIME6 Register Field Descriptions

Bit	Field	Туре	Reset	Description
23	Parity bit	R	0	Parity Bit
22-0	Measurement result	R	0	Measurement result

## 8.6.23 CALIBRATION1: Calibration 1 Register (address: 1Bh ) [reset = 00\_0000h]

## Figure 43. CALIBRATION1 Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit											CALI	BRAT	ION1										
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

## **Table 23. CALIBRATION1 Register Field Descriptions**

Bit	Field	Туре	Reset	Description
23	Parity Blt	R	0	Parity Bit
22-0	CALIBRATION1	R	0	Calibration 1 Result: 23 bit integer value (Bit 22: MSB, Bit 0: LSB)

## 8.6.24 CALIBRATION2: Calibration 2 Register (address: 1Ch ) [reset = 00\_0000h]

#### Figure 44. CALIBRATION2 Register

23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Parity Bit											CALI	BRAT	ION2										
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

## **Table 24. CALIBRATION2 Register Field Descriptions**

Bit	Field	Туре	Reset	Description
23	Parity Blt	R	0	Parity Bit
22-0	CALIBRATION2	R	0	Calibration 2 Result: 23 bit integer value (Bit 22: MSB, Bit 0: LSB)



## 9 Application and Implementation

#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

## 9.1 Application Information

In the Time Of Flight (TOF) method, the upstream flight time as well as the downstream flight time is measured. The difference between the Downstream and Upstream values is proportional to the flow.

The microcontroller (MCU) configures the TDC and AFE and issues a measurement start command to the TDC via the SPI interface. The TDC sends a TRIGGER pulse to the AFE which is set up to actuate one of the transducers and transmit a START signal to the TDC which starts its counter(s). The echo pulse will travel through the AFE and arrive to the TDC as the STOP signal. The counter will be stopped and after performing calibration, the counter value is reported as VAL.

Depending on system implementation, the above procedure is repeated for the same direction or opposite direction.

#### 9.2 Typical Application

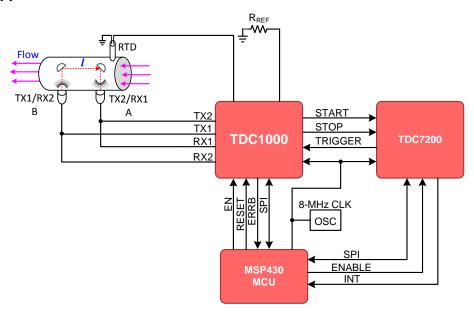


Figure 45. System in Time of Flight Mode

#### 9.2.1 Design Requirements

The parameters in this section are considered for this example.

**Table 25. Design Parameters** 

DESIGN PARAMETER	EXAMPLE VALUE
Pipe diameter	15 mm
Distance between transducers	60 mm
Minimum flow rate	0.015 m <sup>3</sup> /h
Accuracy at minimum flow rate	5%



The design of flow-meters requires a thorough technical assessment of the system where the device will be used. The following is a list of areas to consider:

- Minimum and maximum flow rate at maximum allowable error in the system
- Transitional flow rate
- Instantaneous and total quantity pumped over time
- Accuracy of the meter within prescribed limits per applicable standards
- · Pressure in the system
- · Operating temperature range

The appropriate ultrasonic sensor and the proper electronics for interfacing to the sensor are determined based on the system requirements. The following is a list of specifications applicable to the senor/assembly used in the system:

- Excitation frequency
- Excitation source voltage
- Pipe diameter
- Distance between the transducers (or reflectors)

#### 9.2.2 Detailed Design Procedure

The following subsections describe the detailed design procedure for a flow meter application.

#### 9.2.2.1 Flow Meter Regulations and Accuracy

If the flow meter is intended for residential applications, it must be designed to meet the required standards. For example, per the INTERNATIONAL ORGANIZATION OF LEGAL METROLOGY (OIML), the metrological requirements of water meters are defined by the values of Q1, Q2, Q3 and Q4, which are described in Table 26.

FLOW-RATE ZONE	DESCRIPTION
Q1	Lowest flow rate at which the meter is to operate within the maximum permissible errors.
Q2	Flow rate between the permanent flow rate and the minimum flow rate that divides the flow rate range into two zones, the upper flow rate zone and the lower flow rate zone, each characterized by its own maximum permissible errors.
Q3	Highest flow rate within the rated operating condition at which the meter is to operate within the maximum permissible errors.
Q4	Highest flow rate at which the meter is to operate for a short period of time within the maximum permissible errors, while maintaining its metrological performance when it is subsequently operating within the rated operating conditions.

Table 26. Flow-rate Zones per OIML

A water meter is designated by the numerical value of Q3 in m<sup>3</sup>/h and the ratio Q3/Q1. The value of Q3 and the ratio of Q3/Q1 are selected from the lists provided in the OIML standards.

Water meters have to be designed and manufactured such that their errors do not exceed the maximum permissible errors (MPE) defined in the standards. For example, in OIML standards, water meters need to be designated as either accuracy class 1 or accuracy class 2, according to the requirements.

For class 1 water meters, the maximum permissible error in the upper flow rate zone (Q2  $\leq$  Q4) is  $\pm$ 1%, for temperatures from 0.1°C to 30°C, and  $\pm$ 2% for temperatures greater than 30°C. The maximum permissible error for the lower flow-rate zone (Q1  $\leq$  Q < Q2) is  $\pm$ 3%, regardless of the temperature range.

For class 2 water meters, the maximum permissible error for the upper flow rate zone (Q2  $\leq$  Q4) is  $\pm$ 2%, for temperatures from 0.1°C to 30°C, and  $\pm$ 3% for temperatures greater than 30°C. The maximum permissible error for the lower flow rate zone (Q1  $\leq$  Q < Q2) is  $\pm$ 5% regardless of the temperature range.

The flow meter accuracy specified in the standards dictates the required accuracy in the electronics used for driving the ultrasonic transducers, circuits in the receiver path, and time measurement sub circuits. The stringent accuracy required at lower flow rates would require a very low noise signal chain in the transmitter and receiver circuits used in ultrasonic flow meters, as well as the ability to measure picosecond time intervals.



#### 9.2.2.2 Transmit Time in Ultrasonic Flow Meters

Transit-time ultrasonic flow meters works based on the principle that sound waves in a moving fluid travel faster in the direction of flow (downstream), and slower in the opposite direction of flow (upstream).

The system requires at least two transducers. The first transducer operates as a transmitter during the upstream cycle and as a receiver during the downstream cycle, and the second transducer operates as a receiver during the upstream cycle and as a transmitter during the downstream cycle. An ultrasonic flow meter operates by alternating transmit and receive cycles between the pair of transducers and accurately measuring the time-of-flight both directions.

In this example, the upstream TOF is defined as:

$$t_{BA} = \frac{l}{(c-v)}$$

where

- / is the path length between the two transducers in meters (m)
- c is the speed of sound in water in meters per second (m/s)
- v is the velocity of the water in the pipe in meters per second (m/s) (4)

In this example, the downstream TOF is defined as:

$$t_{AB} = \frac{l}{(c+v)}$$

where

- / is the path length between the two transducers in meters (m)
- c is the speed of sound in water in meters per second (m/s)
- v is the velocity of the water in the pipe in meters per second (m/s) (5)

The difference of TOF is defined as:

$$\Delta TOF = t_{BA} - t_{AB}$$

where

- $t_{BA}$  is the upstream TOF from transducer B to transducer A in seconds (s)
- t<sub>AR</sub> is the downstream TOF from transducer A to transducer B in seconds (s)

After the difference in time-of-flight ( $\Delta$ TOF) is calculated, the water velocity inside the pipe can be related to the  $\Delta$ TOF using the following equation:

$$v = \frac{\Delta TOF \times c^2}{2 \times l}$$

where

- c is the speed of sound in water in meters per second (m/s)
- / is the path length between the two transducers in meters (m)

Finally, the mass flow rate can be calculated as follows:

$$Q = k \times v \times A$$

where

- k is the flow-meter constant
- *v* is the velocity of the water in the pipe in meters per second (m/s)
- A is the cross-section area of the pipe in meters-squared (m<sup>2</sup>)

#### 

Based on the minimum mass flow requirement and accuracy requirements in Table 25, the  $\Delta$ TOF accuracy needed can be calculated as follows:

1. Convert the mass flow rate to m<sup>3</sup>/s:

(7)

(8)



$$Q = (0.015 \, m^3/h) \left( \frac{1 \, h}{3600 \, s} \right) = 4.167 x 10^{-6} \, m^3/s$$

2. Calculate the flow velocity assuming k = 1:

$$v = \frac{Q}{kA} = \frac{4.167 \times 10^{-6} \ m^3/s}{\pi \left(\frac{0.015 \ m}{2}\right)^2} = 0.0236 \ m/s$$

3. Calculate the  $\Delta$ TOF for the given speed of sound. In this example, a speed of sound c = 1400 m/s is assumed:

$$\Delta TOF = \frac{2 \times l \times v}{c^2} = \frac{(2)(0.06 \, m)(0.0236 \, m/s)}{1400 \, m/s^2} = 1.445 \, ns$$

4. The requirement of 5% accuracy for minimum flow will result in a ΔTOF accuracy of:

$$\Delta TOF_{error} = (0.05)(1.445 \, ns) = 72.25 \, ps$$

For this reason, this system requires a high accuracy timer/stopwatch that can measure the lower flow rate state.

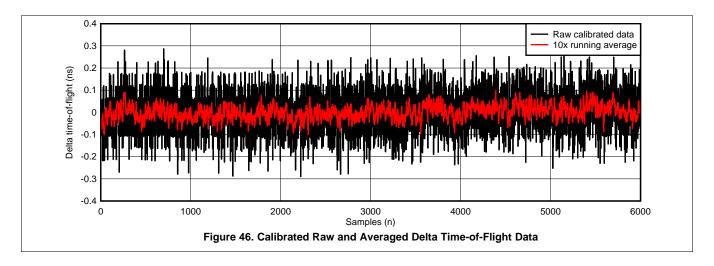
The TDC1000 ultrasonic analog-front-end is used to drive the transmitter, amplify and filter the received signal and conditioning the echo for START and STOP pulse generation. The TDC7200 ps-accurate timer is used to measure the time interval between the rising edge of the START pulse and the rising edge of the STOP pulse produced by the TDC1000.

The microcontroller should first configure the TDC7200 and the TDC1000 for the measurement. When the microcontroller issues a start command to the TDC7200 via the SPI interface, the TDC7200 sends a trigger pulse to the TRIGGER pin of the TDC1000. When the TDC1000 drives the transmit transducer, a synchronous START pulse is produced on the START pin, which commands the TDC7200 to start its counters. When a valid echo pulse is received on the receive transducer, the TDC1000 generates a STOP pulse on the STOP pin, which commands the TDC7200 to stop its counters. This procedure is repeated for the upstream and downstream cycles.

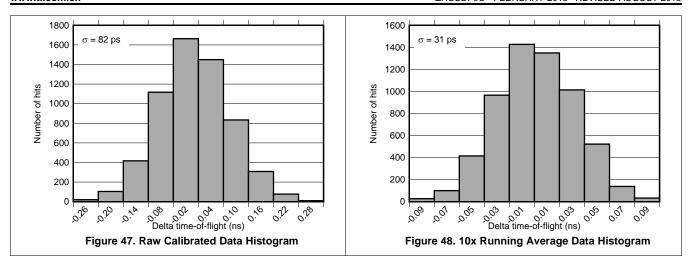
A temperature measurement can be performed and the result can be used to correct for temperature dependency of the speed of sound.

#### 9.2.3 Application Curves

Figure 46, Figure 47, and Figure 48 show data and histograms created with data collected under a zero flow condition at room temperature. A simple offset calibration has been applied, where the overall average of the data is subtracted from the data.







### 9.3 Post Filtering Recommendations

For application such as flow meters where conversion results are accumulated over a long period of time, post filtering is not required. However, for applications where a specific action is taken based on individual conversion results, post filtering is recommended. One advantage of post filtering is to remove the conversion results that are outside of the normal distribution.

One such post filtering method commonly applied by an MCU is the Median Filter Method. The median of a finite number of conversion results can be found by arranging all the conversions from the lowest value to the highest value, and picking the middle one. For example, a conversion result of {50, 51, 49, 40, 51} can be rearranged from lowest to highest {40, 49, 50, 51, 51}, and the median value after applying the Median Filter Method is 50.

#### 9.4 CLOCK Recommendations

A stable, known reference clock is crucial to the ability to measure time, regardless of the time measuring device. Two parameters of a clock source primarily affect the ability to measure time: accuracy and jitter. The following subsections will discuss recommendations for the CLOCK in order to increase accuracy and reduce jitter.

#### 9.4.1 CLOCK Accuracy

CLOCK sources are typically specified with an accuracy value as the clock period is not exactly equal to the nominal value specified. For example, an 8 MHz clock reference may have a 20 ppm accuracy. The true value of the clock period therefore has an error of  $\pm 20$ ppm, and the real frequency is in the range 7.99984 MHz to 8.00016 MHz [8 MHz  $\pm$  (8 MHz) x (20/10<sup>6</sup>)].

If the clock accuracy is at this boundary, but the reference time used to calculate the time of flight relates to the nominal 8 MHz clock period, then the time measured will be affected by this error. For example, if the time period measured is 50  $\mu$ s, and the 8MHz reference clock has +50ppm of error in frequency, but the time measured refers to the 125 ns period (1/8 MHz), then the 50  $\mu$ s time period will have an error of 50 $\mu$ s x 50/1000000 = 2.5 ns.

In summary, a clock inaccuracy translates proportionally to a time measurement error.

#### 9.4.2 CLOCK Jitter

Clock jitter introduces uncertainty into a time measurement, rather than inaccuracy. As shown in Figure 49, the jitter accumulates on each clock cycle so the uncertainty associated to a time measurement is a function of the clock jitter and the number of clock cycles measured.

Clock\_Jitter\_Uncertainty =  $(\sqrt{n}) \times (\theta_{JITTER})$ , where n is the number of clock cycles counted, and  $\theta_{JITTER}$  is the cycle-to-cycle jitter of the clock.

For example, if the time measured is 50 µs using an 8 MHz reference clock, n = 50 µs/(1/8 MHz) = 400 clock cycles. If the RMS cycle-to-cycle jitter,  $\theta_{\text{JITTER}}$  = 10 ps, then the RMS uncertainty introduced in a single measurement is in the order of  $(\sqrt{n})$  x  $(\theta_{\text{JITTER}})$  = 200 ps.



## **CLOCK Recommendations (continued)**

Because the effect of jitter is random, averaging or accumulating time results reduces the effect of the uncertainty introduced. If the time is measured m times and the result is averaged, then the uncertainty is reduced to: Clock\_Jitter\_Uncertainty =  $(\sqrt{n}) \times (\theta_{JITTER}) / (\sqrt{m})$ .

For example, if 64 averages are performed in the example above, then the jitter-related uncertainty is reduced to 25 ps RMS.

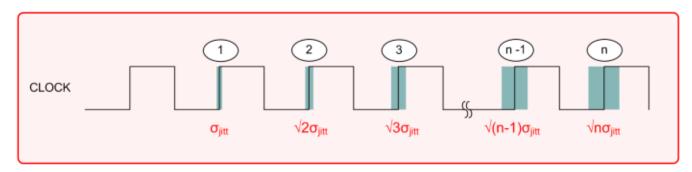


Figure 49. CLOCK Jitter



## 10 Power Supply Recommendations

The analog circuitry of the TDC7200 is designed to operate from an input voltage supply range between 2 V and 3.6 V. It is recommended to place a 100 nF ceramic bypass capacitor to ground as close as possible to the VDD pins. In addition, an electrolytic or tantalum capacitor with value greater than 1  $\mu$ F is recommended. The bulk capacitor does not need to be in close vicinity with the TDC7200 and could be close to the voltage source terminals or at the output of the voltage regulators powering the TDC7200.

## 11 Layout

### 11.1 Layout Guidelines

- In a 4-layer board design, the recommended layer stack order from top to bottom is: signal, ground, power and signal.
- Bypass capacitors should be placed in close proximity to the VDD pin.
- The length of the START and STOP traces from the TDC7200 to the stopwatch/MCU should be matched to prevent uneven signal delays. Also, avoid unnecessary via-holes on these traces and keep the routing as short/direct as possible to minimize parasitic capacitance on the PCB.
- Route the SPI signal traces close together. Place a series resistor at the source of DOUT (close to the TDC7200) and series resistors at the sources of DIN, SCLK, and CSB (close to the master MCU).



## 11.2 Layout Example

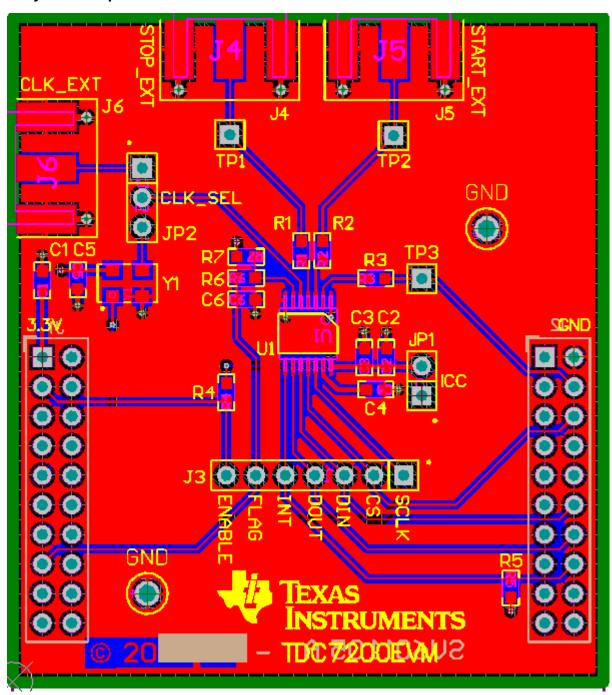


Figure 50. TDC7200EVM Layout



## 12 器件和文档支持

#### 12.1 文档支持

#### 12.1.1 相关文档

相关文档如下:

• TDC1000: 面向液位、浓度、流量和接近感测应用的超声波感测模拟前端。

#### 12.2 社区资源

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

#### 12.3 商标

E2E is a trademark of Texas Instruments.

SPI is a trademark of Motorola.

All other trademarks are the property of their respective owners.

#### 12.4 静电放电警告



这些装置包含有限的内置 ESD 保护。 存储或装卸时,应将导线一起截短或将装置放置于导电泡棉中,以防止 MOS 门极遭受静电损伤。

## 12.5 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

## 13 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。 这些信息是针对指定器件可提供的最新数据。 这些数据会在无通知且不对本文档进行修订的情况下发生改变。 要获得这份数据表的浏览器版本,请查阅左侧的导航栏。

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
TDC7200PW	Active	Production	TSSOP (PW)   14	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	T7200
TDC7200PW.A	Active	Production	TSSOP (PW)   14	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	T7200
TDC7200PWR	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	T7200
TDC7200PWR.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	T7200
TDC7200PWRG4	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	T7200
TDC7200PWRG4.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	T7200

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



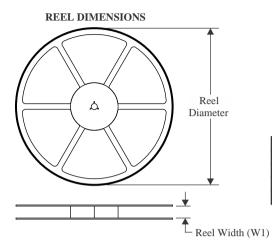
## **PACKAGE OPTION ADDENDUM**

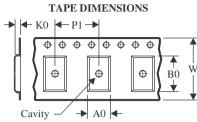
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## **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

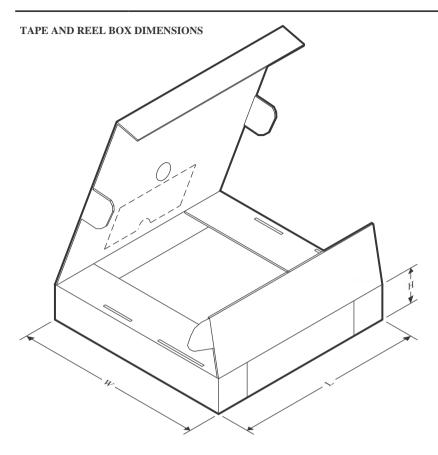


#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TDC7200PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TDC7200PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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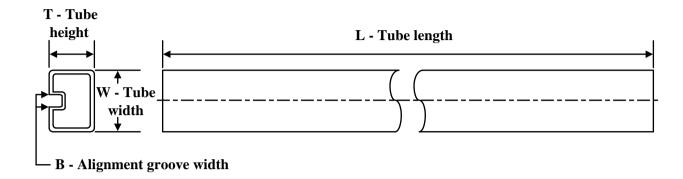
## \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
TDC7200PWR	TSSOP	PW	14	2000	350.0	350.0	43.0	
TDC7200PWRG4	TSSOP	PW	14	2000	350.0	350.0	43.0	

# **PACKAGE MATERIALS INFORMATION**

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## **TUBE**

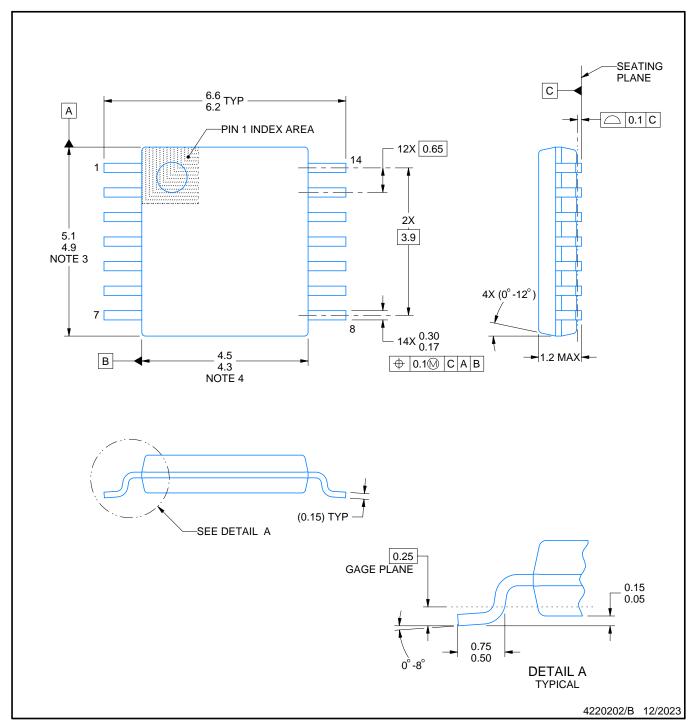


### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TDC7200PW	PW	TSSOP	14	90	530	10.2	3600	3.5
TDC7200PW.A	PW	TSSOP	14	90	530	10.2	3600	3.5



SMALL OUTLINE PACKAGE



#### NOTES:

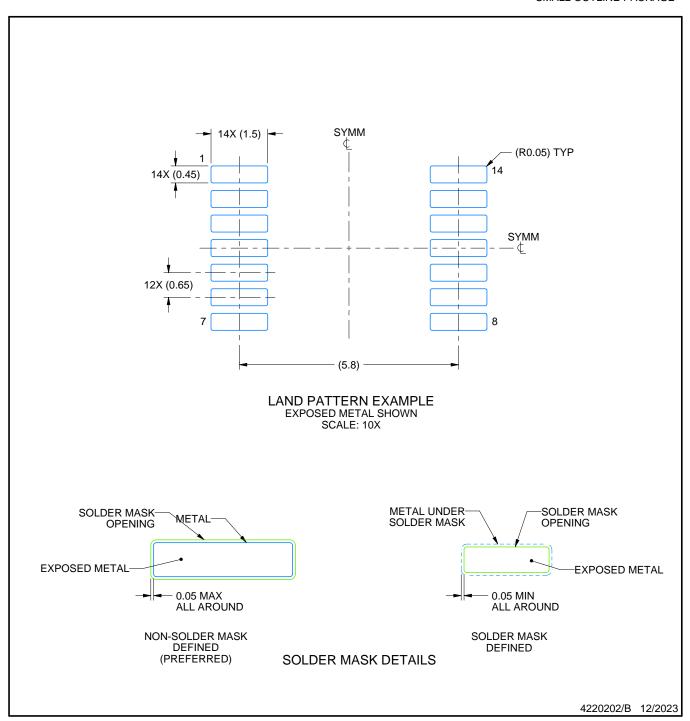
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



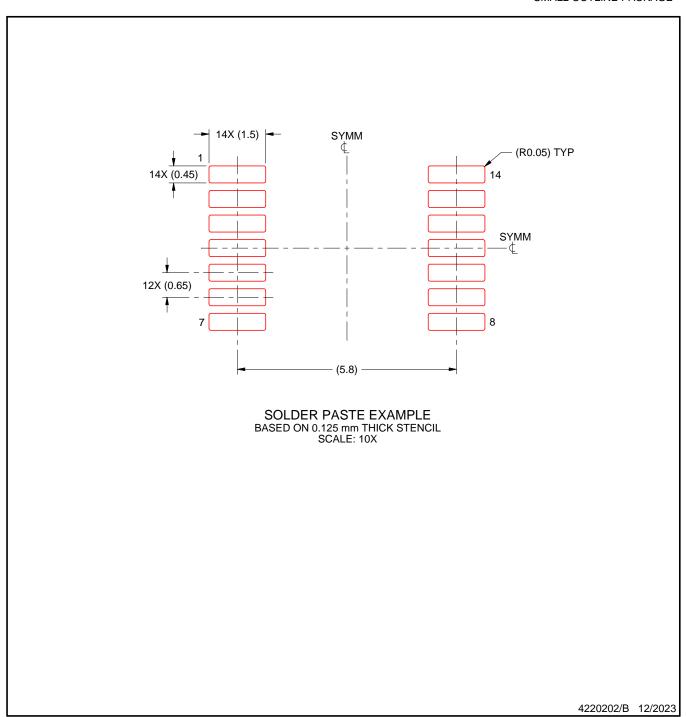
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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